



Atty. Docket No. UMC-98-254 CON2
Client Matter No. 81848.0019.002
Express Mail Label No. EL 936770685 US

In re Application of:

Kun-Lin WU, et al

Serial No. 09/990,948

Filed: November 20, 2001

For: CHEMICAL-MECHANICAL
POLISHING METHOD

Examiner: Unassigned

Art Unit: Unassigned

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SECOND PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Pursuant to 37 C.F.R. § 1.115, this Second Preliminary Amendment is submitted in supplement to a Preliminary Amendment filed November 20, 2001, in the above-identified application, before the first examination and action on such application. Entry of the following amendment is respectfully requested:

IN THE CLAIMS:

Please add the following new claims 45-54:

B1
45. (New) A chemical mechanical polishing process, comprising the steps of:

(a) forming a conductive layer over a semiconductor substrate; and

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